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PATENT
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ABSTRACT

High-speed transfer of chip components is possible and a drive mechanism can be made simple and small-sized with reduced oscillations by the transfer apparatus of chip components disclosed herein. A transfer disc 1 is disposed so that it may be inclined to a horizontal surface, and the disc has a transfer groove 11 on the upper surface thereof, and has a cavity 12 at the periphery edge part of the transfer groove 11. A chip component C is made to fall into the transfer groove 11 in connection with the rotation of the transfer disc 1. The chip components are aligned in a predetermined direction, and one chip component is maintained in a cavity 12 by effect of gravity. A conveying disc 2 has cavities 21 for receiving chip components C from the transfer disc 1. Those cavities are provided at an equal pitch interval in the outer peripheral portions of the disc. When receiving chip-component C from the transfer disc 1 to each cavity 21, this cavity has an air suction hole 22 which performs an adsorption hold. Synchronization is maintained and a continuous drive of the transfer disc 1 and the conveying disc 2 is performed so that both cavities 12 and 21 oppose each other.

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